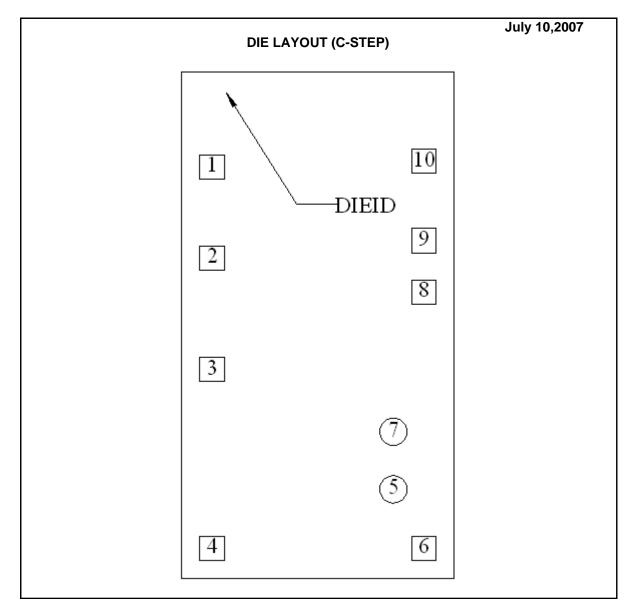


LP2951C MWC SERIES OF ADJUSTABLE MICROPOWER VOLTAGE REGULATORS



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General D	General Die Information		
Physical Die Identification	LP20C	Bond Pad Opening Size (min)	80µm x 80µm		
Die Step	С	Bond Pad Metalization	0.5%COPPER_BAL. ALUMINUM		
Physical Attributes		Passivation	VOM NITRIDE		
Wafer Diameter	150mm	Back Side Metal	Bare Back		
Die Size (Drawn)	904µm x 1684µm 35.6mils x 66.3mils	Back Side Connection	GND		
Thickness	330µm Nominal		-		
Min Pitch	170μm Nominal				

Special Assembly Requirements: Note: Actual die size is rounded to the nearest micron.



LP2951C MWC

SERIES OF ADJUSTABLE MICROPOWER VOLTAGE REGULATORS

	Die Bond Pad Coordinate Locations (C -Step)					
(Referenced to	(Referenced to die center, coordinates in μ m) NC = No Connection, N.U. = Not Used					
SIGNAL	PAD#	X/Y CC	ORDINATES		PAD :	SIZE
NAME	NUMBER	Х	Y	Х		Υ
OUTPUT	1	-352	525	80	х	80
SENSE	2	-352	223	80	х	80
SHUTDOWN	3	-352	-149	80	х	80
GND	4	-352	-742	80	х	80
NC	5	250	-547	91	х	91
ERROR	6	352	-742	80	х	80
NC	7	250	-355	91	х	91
VTAP	8	351	110	80	х	80
FEEDBACK	9	352	280	80	х	80
INPUT	10	352	544	80	х	80



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